# Material Data Declaration Sheet - v003

*Version 2.0*

## Supplier Information

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|---|---|
| **Company Name *** | Intel Corporation |
| **Response Document ID** | 109625 |
| **Company Unique ID** | 047897855 |
| **Unique ID Authority** | Dun and Bradstreet |
| **Response Date *** | 2026-04-29 |

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| **Contact Name *** | Ooi, Khye Lin |
| **Contact Title *** | Intel Product Ecology |
| **Contact Phone *** | 1-800-628-8686 |
| **Contact Email *** | productecology@intel.com |

**Supplier Comments**

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## Product(s)

**Product Family Name:**

| Requester Item Number | Item Number * | Description | Effective Date * | Mass * | UoM* | Comment |
|---|---|---|---|---|---|---|
| | A3CZ100BB23XXXX | Agilex™ 3 FPGA C-Series 100 (B23C) | 2026-04-29 | 1.409 | g | |

**Product Part(s)**

| ID* | Description | Effective Date* | Units* | % of Product Mass | Comment | |
|---|---|---|---|---|---|---|
| Die | Die | 2026-04-29 | 1 | 8.792 | | |
| Solder Spheres | Solder Spheres | 2026-04-29 | 1 | 6.938 | | |
| Substrate | Substrate | 2026-04-29 | 1 | 82.141 | | |
| Underfill | Underfill | 2026-04-29 | 1 | 2.129 | | |

## Declaration

| | | |
|---|---|---|
| LHPLA | This product is Low Halogen (Components): Applies only to brominated and chlorinated flame retardants (BFRs/CFRs) and PVC in the final product. The replacement of halogenated flame retardants may not be better for the environment. Intel Components as well as purchased components on the finished assembly meet the joint JEDEC/ECA JS-709B requirement. | True |
| LHPWB | This product is Low Halogen (PCB): Applies Br/Cl in the PCB Laminate. The PCB / Substrate meet IEC 61249-2-21 requirements. The replacement of halogenated flame retardants may not be better for the environment | True |
| REACH-0226 | Product(s) is obsolete, no information is available | False |
| REACH-0226 | Product(s) is unknown, no information is available | False |
| REACH-0226 | Product(s) does not contain EU REACH Candidate List substances above the thresholds specified in the REACH Regulation | True |
| EUROHS-1506 | Product(s) does not meet EU RoHS requirements and is not under exemptions | False |
| EUROHS-1506 | Product(s) is obsolete, No Information is Available | False |
| EUROHS-1506 | Product(s) is unknown, no information is available | False |
| EUROHS-1506 | Product(s) Meets EU RoHS Requirements by Application of the Selected Exemption(s) | False |
| EUROHS-1506 | Product(s) Meets EU RoHS Requirements Without Any Exemptions | True |

## Signature

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|---|---|
| Intel Product Ecology | C=US, E=productecology@intel.com, OU="", O=Intel Corporation, CN=Intel Product Ecology |

| Part ID | Description | | # of Units | Part Mass % |
|---|---|---|---|---|
| Die | Die | | 1 | 8.792 |

| Homogenous Material Name | Material Class ID | HM Mass UoM | HM Mass Value | Substance Group | Substance Identity | Substance | Substance Mass UoM | Substance Mass Value | Exemption |
|---|---|---|---|---|---|---|---|---|---|
| Die Silicon Material (Generic) | | massPercent | 99.200 | | | Proprietary Doped Silicon | ppm | 1000000.000 | |
| Passivation Layer (143907-02-2) | | massPercent | 0.800 | 00193 | 143907-02-2 | Poly(oxy-1,2-ethanediyl), α,α',α'',α'''-(oxydi-3,1,2- | ppm | 1700.000 | |
| | | | | | | Proprietary ingredients | ppm | 998300.000 | |

| Part ID | Description | | # of Units | Part Mass % |
|---|---|---|---|---|
| Solder Spheres | Solder Spheres | | 1 | 6.938 |

| Homogenous Material Name | Material Class ID | HM Mass UoM | HM Mass Value | Substance Group | Substance Identity | Substance | Substance Mass UoM | Substance Mass Value | Exemption |
|---|---|---|---|---|---|---|---|---|---|
| ECO SOLDER BALL S #7097 0.3mm | | mg | 97.755 | | 7440-50-8 | Copper | ppm | 5000.000 | |
| | | | | | 7440-22-4 | Silver | ppm | 40000.000 | |
| | | | | | 7440-31-5 | Tin | ppm | 955000.000 | |

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| Part ID | Description | | # of Units | Part Mass % |
|---|---|---|---|---|
| Substrate | Substrate | | 1 | 82.141 |

| Homogenous Material Name | Material Class ID | HM Mass UoM | HM Mass Value | Substance Group | Substance Identity | Substance | Substance Mass UoM | Substance Mass Value | Exemption |
|---|---|---|---|---|---|---|---|---|---|
| ABF | | g | 0.126 | | | Epoxy Resin | ppm | 360000.000 | |
| | | | | | 7631-86-9 | Silicon Dioxide | ppm | 600000.000 | |
| | | | | | 64742-94-5 | Solvent Naphtha ( Petroleum), Heavy Aroma | ppm | 40000.000 | |
| Copper | | g | 0.602 | | 7440-50-8 | Copper | ppm | 1000000.000 | |
| Core | | g | 0.403 | | | Epoxy Resin | ppm | 350000.000 | |
| | | | | | 65997-17-3 | Fibrous-Glass-Wool | ppm | 450000.000 | |
| | | | | | 7631-86-9 | Silicon Dioxide | ppm | 200000.000 | |
| Gold | | g | 0.000 | | 7440-57-5 | Gold | ppm | 1000000.000 | |
| Nickel | | g | 0.005 | 00031 | 7440-02-0 | Nickel | ppm | 1000000.000 | |
| Palladium | | g | 0.000 | | 7440-05-3 | Palladium | ppm | 1000000.000 | |
| Solder mask | | g | 0.021 | | 7727-43-7 | Barium Sulfate | ppm | 180000.000 | |
| | | | | | | Epoxy Resin | ppm | 820000.000 | |

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| Part ID | Description | | # of Units | Part Mass % |
|---|---|---|---|---|
| Underfill | Underfill | | 1 | 2.129 |

| Homogenous Material Name | Material Class ID | HM Mass UoM | HM Mass Value | Substance Group | Substance Identity | Substance | Substance Mass UoM | Substance Mass Value | Exemption |
|---|---|---|---|---|---|---|---|---|---|
| XS8410-428ND | | mg | 30.000 | | 25068-38-6 | (CHLOROMETHYL)OXIRANE, 4,4'-(1- | ppm | 6100.000 | |
| | | | | | 27610-48-6 | 6-glycidyloxynapht-1-yl oxymethyloxirane | ppm | 35000.000 | |
| | | | | | | Additives | ppm | 8700.000 | |
| | | | | | | Amine type hardener | ppm | 85000.000 | |
| | | | | | 9003-36-5 | FORMALDEHYDE, POLYMER WITH (CHLOROMETHYL)OXIRANE | ppm | 190000.000 | |
| | | | | | 603-35-0 | Phosphine, triphenyl- | ppm | 1900.000 | |
| | | | | | 60676-86-0 | Silica, Vitreous | ppm | 673300.000 | |